Notice of Allowability	Application No.	Applicant(s)	
	10/803,009	PATIL ET AL.	
	Examiner	Art Unit	
	Thanh Y. Tran	2822	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address--

All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. **THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS.** This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.

1. ☐ This communication is responsive to _____.

2. ☒ The allowed claim(s) is/are *1-7,10-15 and 18-22*.

3. ☒ The drawings filed on *17 March 2004* are accepted by the Examiner.

4. ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
   a) ☐ All b) ☐ Some* c) ☐ None of the:
      1. ☐ Certified copies of the priority documents have been received.
      2. ☐ Certified copies of the priority documents have been received in Application No. _____ .
      3. ☐ Copies of the certified copies of the priority documents have been received in this national stage application from the International Bureau (PCT Rule 17.2(a)).

   * Certified copies not received: _____.

Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application.
THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.

5. ☐ A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.

6. ☐ CORRECTED DRAWINGS (as "replacement sheets") must be submitted.
   (a) ☐ including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached
      1) ☐ hereto or 2) ☐ to Paper No./Mail Date _____.
   (b) ☐ including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date _____.

Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d).

7. ☐ DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.

Attachment(s)

1. ☒ Notice of References Cited (PTO-892)
2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948)
3. ☒ Information Disclosure Statements (PTO-1449 or PTO/SB/08), Paper No./Mail Date 3/17/04
4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material
5. ☐ Notice of Informal Patent Application (PTO-152)
6. ☒ Interview Summary (PTO-413), Paper No./Mail Date _____ .
7. ☒ Examiner's Amendment/Comment
8. ☒ Examiner's Statement of Reasons for Allowance
9. ☐ Other _____.

AMIR ZARABIAN
SUPERVISORY PATENT EXAMINER
TECHNOLOGY CENTER 2800

DETAILED ACTION

EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Mr. Scott Barker on 11/24/04.

The application has been amended as follows:

Claims 8-9, 16-17, and 23-24 have been canceled.

Allowable Subject Matter

2. Claims 1-7, 10-15, and 18-22 are allowed.

3. The following is an examiner's statement of reasons for allowance:

In claim 1, the patentability, at least in part, is a combination of: *"a process for forming one or more fluid feed vias in a semiconductor substrate chip for a micro-fluid ejection device, the process comprising the steps of: applying a photoresist planarization and protection layer having a thickness ranging from about 1 to about 10 microns to a first surface of the chip; patterning and developing the photoresist planarization and protection layer to define at least one fluid feed via location; applying a strippable masking layer having a thickness ranging from about 10 to about 100 microns to the photoresist planarization and protection layer of the chip; patterning and developing the strippable masking layer to define the at least one fluid feed via location in the strippable masking layer; dry etching the chip to form at least one fluid feed via*

in the defined fluid feed via location; ***inducing deprotection of the strippable masking layer before or after the step of dry etching the chip so that the strippable masking layer can be substantially removed without affecting the photoresist planarization and protection layer".***

In claim 10, the patentability, at least in part, is a combination of: *"a process for forming an ink feed via in a semiconductor substrate chip for an ink jet printhead, the process comprising the steps of: applying a photoresist planarization and protection layer having a thickness ranging from about 1 to about 10 microns to a first surface of the chip; patterning and developing the photoresist planarization and protection layer to define at least one ink feed via location; applying a strippable photoresist layer having a thickness ranging from about 10 to about 100 microns to the photoresist planarization and protection layer of the chip; patterning and developing the strippable photoresist layer with a photomask to define the at least one ink feed via location in the strippable photoresist layer; dry etching the chip to form at least one ink feed via in the defined at least one ink feed via location;* ***inducing deprotection of the strippable photoresist layer before or after the step of dry etching the chip using radiant energy so that the strippable photoresist layer can be substantially removed without affecting the photoresist planarization and protection layer".***

In claim 18, the patentability, at least in part, is a combination of: *"a process for forming one or more ink feed vias in a semiconductor substrate chip for use in an ink jet printhead, the process comprising the steps of: applying a photoresist planarization and protection layer having a thickness ranging from about 1 to about 10 microns to a first surface of the chip; patterning and developing the photoresist planarization and protection layer to define at least one ink feed via location; applying a strippable photoresist layer having a thickness ranging*

from about 10 to about 100 microns to the photoresist planarization and protection layer of the chip; patterning and developing the strippable photoresist layer with a photomask to define the at least one ink feed via location in the strippable photoresist layer; dry etching the chip to form at least one ink feed via in the defined at least one ink feed via location; ***inducing deprotection of the strippable photoresist layer before or after the step of dry etching the chip using a compound selected from the group consisting of an organic acid, an inorganic acide, and other positively charged species sufficient to deprotect the strippable photoresist layer so that the strippable photoresist layer can be substantially removed with a solvent without affecting the photoresist planarization and protection layer".***

4. The art of record does not disclose the above limitations, nor would it be obvious to modify the art of record so as to include the above limitations.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Contact Information

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thanh Y. Tran whose telephone number is (571) 272-2110. The examiner can normally be reached on M-F (9-6:30pm).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on (571) 272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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